

### **Remarks**

Claims 1, 2, 6-8, 14, and 15 are currently pending in the present application. New Claims 18-23 have been added, wherein Claims 18 and 21 are directed to structures having a reflector layer made of a material comprising metal, Claims 19 and 22 are directed to structures having a reflector layer made of a metal-composite material, and Claims 20 and 23 are directed to structures having a reflector layer made of a metal alloy. Support for new Claims 18-23 can be found, for example, at paragraphs [0031] through [0033] of the specification. The Applicants submit that no new matter has been introduced herein. In view of the foregoing amendments and following remarks, the Applicants request reconsideration and withdrawal of the grounds of rejection.

### **Claim Objections**

Claim 8 is objected to as lacking antecedent basis. Claim 8 has been amended and now has a proper antecedent basis. Accordingly, the Applicants submit that Claim 8 is allowable, and respectfully request reconsideration and withdrawal of this grounds of objection.

### **Claim Rejections under 35 U.S.C. §112**

Claims 1, 2, 6-8, 14, and 15 stand rejected under 35 U.S.C. §112 as being indefinite for failing to clearly identify the relationship between the coefficients of thermal expansion of a reflector layer and an electrically insulating layer. In view of the following remarks, reconsideration and withdrawal of this grounds of rejection is respectfully requested.

Claim 1 as amended recites:

A semiconductor package comprising:

an electrically insulating substrate layer; a non-conductive layer disposed on the electrically insulating substrate layer; and, a reflector layer disposed on the non-conductive layer, wherein the electrically insulating substrate layer includes at least one first metallized portion on a first surface thereof and at least one second metallized portion on a second surface thereof, said second surface opposite said first surface, and wherein the reflector layer is

*made of a metal with a coefficient of thermal expansion which is matched to a coefficient of thermal expansion of a material of the electrically insulating substrate layer.* (emphasis added).

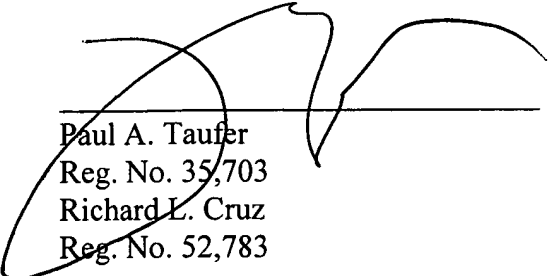
Claim 1 is directed to a semiconductor package comprising a reflector layer made of a metal and electrically insulating substrate layer. As emphasized above, the coefficient of thermal expansion (CTE) of the metal reflector layer is matched with the CTE of a material of the electrically insulating substrate. Since the relationship between the CTEs of the reflector layer and the electrically insulating layer is explicitly recited, the Applicants respectfully submit that Claim 1, including said relationship, is definite in accordance with 35 U.S.C. §112. Accordingly, the Applicants respectfully submit that Claim 1, and Claims 2, and 6-8 which depend thereon, are definite under 35 U.S.C. §112, and respectfully request reconsideration and withdrawal of this grounds of rejection.

Claim 14 as amended recites a light emitting device comprising similar elements as those recited in Claim 1. As such, the Applicants respectfully submit that the relationship between the CTEs of the reflector layer and the electrically insulating layer of Claim 14 is explicitly recited. Therefore, the Applicants respectfully submit that Claim 14, and Claim 15 which depends thereon, are definite under 35 U.S.C. §112, and respectfully request reconsideration and withdrawal of this grounds of rejection.

### **Conclusion**

In view of the forgoing claim amendments and remarks, the Applicants respectfully submit that the present Application, including Claims 1, 2, 6-8, 15, 15, and 18-23, is now in condition for allowance and respectfully request an indication reflecting the same.

Respectfully submitted,



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